12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20140523000
Qualification of Reduced Wire Bond diameter for the Family of Discrete Clip & Power Block Devices
Change Notification / Sample Request

Date: 5/27/2014
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI’s standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140523000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CSD16321Q5	null
CSD16322Q5	null
CSD16323Q3	null
CSD16325Q5	null
CSD16327Q3	null
CSD16340Q3	null
CSD16401Q5	null
CSD16406Q3	null
CSD16407Q5	null
CSD16408Q5	null
CSD16409Q3	null
CSD16411Q3	null
CSD16414Q5	null
CSD16415Q5	null
CSD16556Q5B	null
CSD17303Q5	null
CSD17304Q3	null
CSD17308Q3	null
CSD17309Q3	null
CSD17311Q5	null
CSD17312Q5	null
CSD17556Q5B	null
CSD17559Q5	null
CSD18502Q5B	null
CSD18532NQ5B	null
CSD18532Q5B	null
CSD19502Q5B	null
CSD19532Q5B	null
CSD86330Q3D	null
CSD86350Q5D	null
CSD86360Q5D	null
CSD87330Q3D	null
CSD87331Q3D	null
CSD87333Q3D	null
CSD87350Q5D	null
CSD87351Q5D	null
CSD87351ZQ5D	null
CSD87352Q5D	null
CSD87353Q5D	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140523000	**PCN Date:**	05/27/2014

Title:	Qualification of Reduced Wire Bond diameter for the Family of Discrete Clip & Power Block Devices

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	08/27/2014	**Estimated Sample Availability:**	Date provided upon request

Change Type:

☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification a reduced bond wire diameter for the family of Discrete Clip & Power Block Devices:

	Current	New
Bond Wire/Diameter	Au, 2.0 mil	**Au, 1.0 mil**

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

None

Product Affected

CSD16321Q5	CSD16414Q5	CSD17570Q5B	CSD58869Q5D
CSD16322Q5	CSD16415Q5	CSD17573Q5B	CSD58870Q5D
CSD16323Q3	CSD16515Q5	CSD17575Q3	CSD86330Q3D
CSD16325Q5	CSD16556Q5B	CSD17576Q5B	CSD86350Q5D
CSD16327Q3	CSD16570Q5B	CSD17590Q5B	CSD86360Q5D
CSD16340Q3	CSD17303Q5	CSD18502Q5B	CSD87330Q3D
CSD16341Q5	CSD17304Q3	CSD18509Q5B	CSD87331Q3D
CSD16350Q5	CSD17308Q3	CSD18532NQ5B	CSD87333Q3D
CSD16401Q5	CSD17309Q3	CSD18532Q5B	CSD87350Q5D
CSD16406Q3	CSD17311Q5	CSD18540Q5B	CSD87351Q5D
CSD16407Q5	CSD17312Q5	CSD19502Q5B	CSD87351ZQ5D
CSD16408Q5	CSD17556Q5B	CSD19532Q5B	CSD87352Q5D
CSD16409Q3	CSD17559Q5	CSD58865Q5D	CSD87353Q5D
CSD16411Q3	CSD17566Q3	CSD58867Q3D	

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 1 : CSD87331Q3D (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#200805
# Pins-Designator, Family:	8-DQZ, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0

Notes **- Preconditioning sequence: Level 1-260C.

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 2 : CSD58869Q5D (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQY, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0

Notes **- Preconditioning sequence: Level 1-260C.

Qualification Data – Approved May, 2014

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Reference Qualification# 3 : CSD16407Q5 (MSL 1-260C)

Package Construction Details

Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQH, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0

Notes **- Preconditioning sequence: Level 1-260C.

Qualification Data – Approved May, 2014			
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications**.**			
Reference Qualification# 4 : CSD25401Q3 (MSL 1-260C)			
Package Construction Details			
Assembly Site:	PAC	Mold Compound:	SID#202828
# Pins-Designator, Family:	8-DQG, LSON-CLIP	Mount Solder:	SID#200757
Lead frame (Finish, Base):	Matte Sn, Cu	Bond Wire:	1.0 Mil Dia., Au
Qualification: ☐ **Plan** ☒ **Test Results**			

Reliability Test	Conditions	Sample Size/Fail
**T/C -40C/125C	-40C/+125C (500 Cyc)	77/0
Notes **- Preconditioning sequence: Level 1-260C.		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com